



**ALPHA & OMEGA**  
SEMICONDUCTOR



**AO4616**

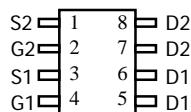
## Complementary Enhancement Mode Field Effect Transistor

### General Description

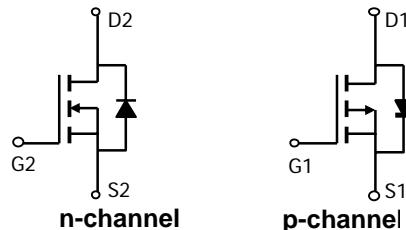
The AO4616 uses advanced trench technology MOSFETs to provide excellent  $R_{DS(ON)}$  and low gate charge. The complementary MOSFETs may be used in inverter and other applications. Standard Product AO4616 is Pb-free (meets ROHS & Sony 259 specifications). AO4616L is a Green Product ordering option. AO4616 and AO4616L are electrically identical.

### Features

n-channel	p-channel
$V_{DS}$ (V) = 30V	-30V
$I_D = 8.1A$ ( $V_{GS} = 10V$ )	-7.1A ( $V_{GS} = -10V$ )
$R_{DS(ON)}$	$R_{DS(ON)}$
< 20mΩ ( $V_{GS} = 10V$ )	< 25mΩ ( $V_{GS} = -10V$ )
< 28mΩ ( $V_{GS} = 4.5V$ )	< 40mΩ ( $V_{GS} = -4.5V$ )



SOIC-8



### Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Max n-channel	Max p-channel	Units
Drain-Source Voltage	$V_{DS}$	30	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	$\pm 20$	V
Continuous Drain Current <sup>A</sup>	$I_D$	8.1	-7.1	A
$T_A=70^\circ C$		6.5	-5.6	
Pulsed Drain Current <sup>B</sup>	$I_{DM}$	30	-30	
Power Dissipation	$P_D$	2	2	W
$T_A=70^\circ C$		1.28	1.28	
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	-55 to 150	°C

### Thermal Characteristics: n-channel and p-channel

Parameter	Symbol	Device	Typ	Max	Units
Maximum Junction-to-Ambient <sup>A</sup>	$R_{\theta JA}$	n-ch	48	62.5	°C/W
Steady-State		n-ch	74	110	°C/W
Maximum Junction-to-Lead <sup>C</sup>	$R_{\theta JL}$	n-ch	35	60	°C/W
Maximum Junction-to-Ambient <sup>A</sup>	$R_{\theta JA}$	p-ch	48	62.5	°C/W
Steady-State		p-ch	74	110	°C/W
Maximum Junction-to-Lead <sup>C</sup>	$R_{\theta JL}$	p-ch	35	40	°C/W

**N-Channel Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	30			V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS}=24\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$		1	5	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm20\text{V}$		100	nA	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1	1.8	3	V
$I_{\text{D(on)}}$	On state drain current	$V_{GS}=10\text{V}, V_{DS}=5\text{V}$	30			A
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_D=8.1\text{A}$ $T_J=125^\circ\text{C}$		16.4	20	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}, I_D=6\text{A}$		20	25	
$g_{\text{FS}}$	Forward Transconductance	$V_{DS}=5\text{V}, I_D=8.1\text{A}$		23		S
$V_{\text{SD}}$	Body-Diode Forward Voltage	$I_S=1\text{A}$		0.75	1	V
$I_S$	Maximum Body-Diode Continuous Current				3	A
<b>DYNAMIC PARAMETERS</b>						
$C_{\text{iss}}$	Input Capacitance			1040	1250	pF
$C_{\text{oss}}$	Output Capacitance	$V_{GS}=0\text{V}, V_{DS}=15\text{V}, f=1\text{MHz}$		180		pF
$C_{\text{rss}}$	Reverse Transfer Capacitance			110		pF
$R_g$	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		0.7		$\Omega$
<b>SWITCHING PARAMETERS</b>						
$Q_g(10\text{V})$	Total Gate Charge			19.2		nC
$Q_g(4.5\text{V})$	Total Gate Charge			9.36		nC
$Q_{\text{gs}}$	Gate Source Charge	$V_{GS}=10\text{V}, V_{DS}=15\text{V}, I_D=8.1\text{A}$		2.6		nC
$Q_{\text{gd}}$	Gate Drain Charge			4.2		nC
$t_{\text{D(on)}}$	Turn-On Delay Time			5.2		ns
$t_r$	Turn-On Rise Time	$V_{GS}=10\text{V}, V_{DS}=15\text{V}, R_L=1.8\Omega,$ $R_{\text{GEN}}=3\Omega$		4.4		ns
$t_{\text{D(off)}}$	Turn-Off Delay Time			17.3		ns
$t_f$	Turn-Off Fall Time			3.3		ns
$t_{\text{rr}}$	Body-Diode Reverse Recovery Time	$I_F=8.1\text{A}, dI/dt=100\text{A}/\mu\text{s}$		16.7	21	ns
$Q_{\text{rr}}$	Body-Diode Reverse Recovery Charge	$I_F=8.1\text{A}, dI/dt=100\text{A}/\mu\text{s}$		6.7	10	nC

A: The value of  $R_{\text{OJA}}$  is measured with the device mounted on 1 in <sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The value in any given application depends on the user's specific board design. The current rating is based on the  $t \leq 10\text{s}$  thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

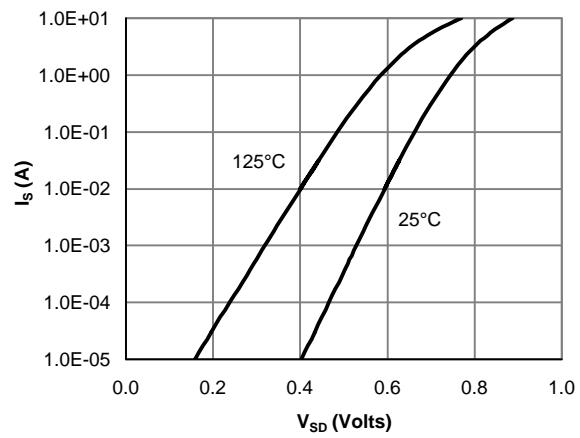
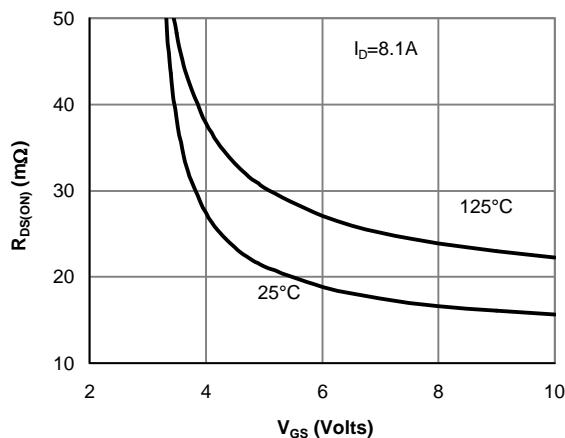
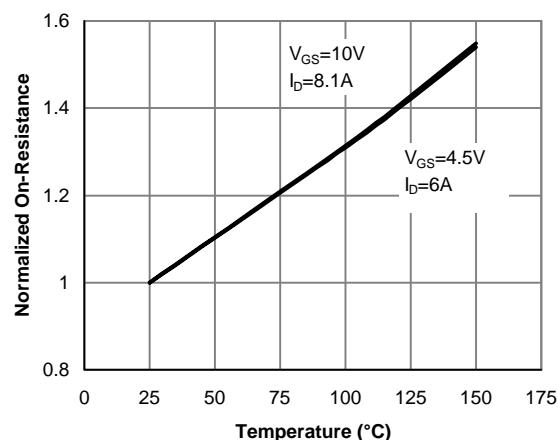
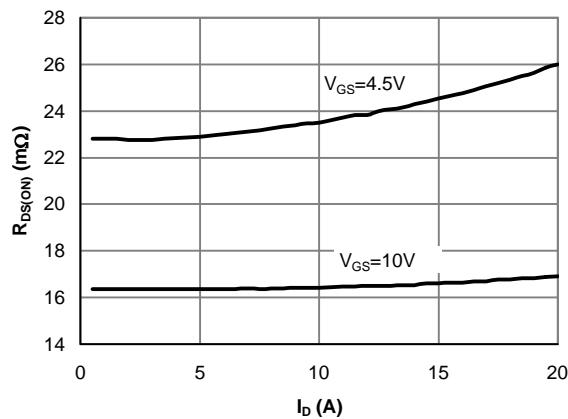
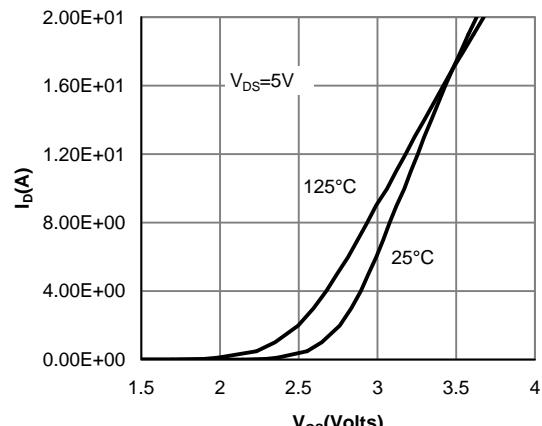
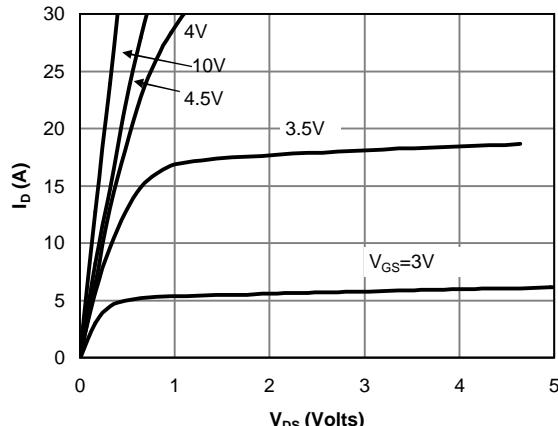
C. The  $R_{\text{OJA}}$  is the sum of the thermal impedance from junction to lead  $R_{\text{JL}}$  and lead to ambient.

D. The static characteristics in Figures 1 to 6 are obtained using 80  $\mu\text{s}$  pulses, duty cycle 0.5% max.

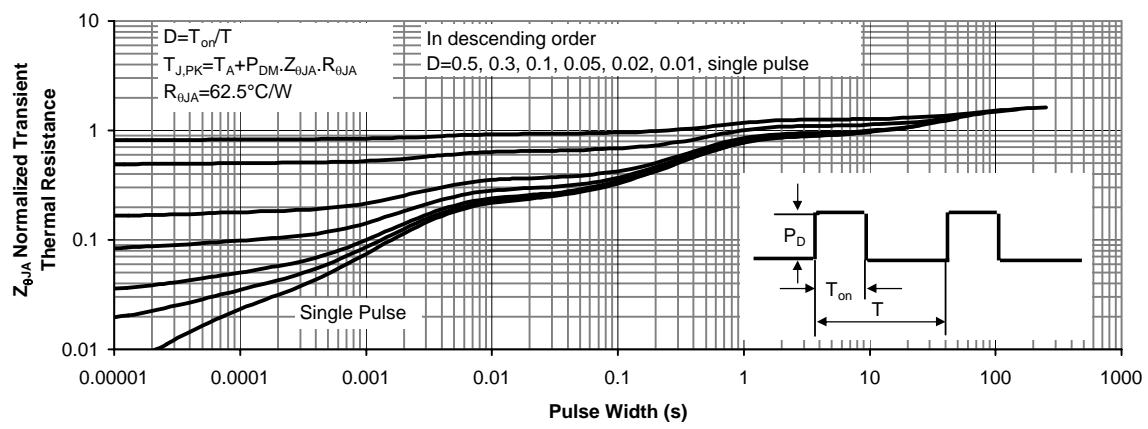
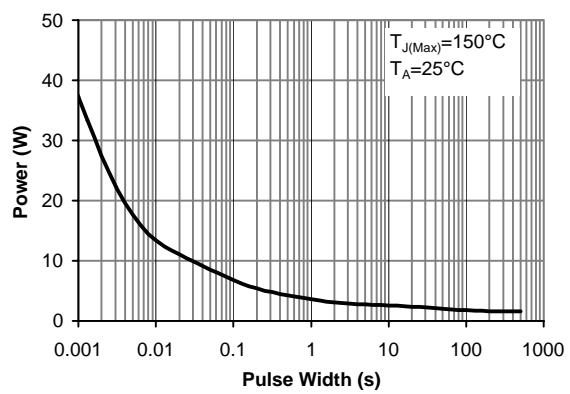
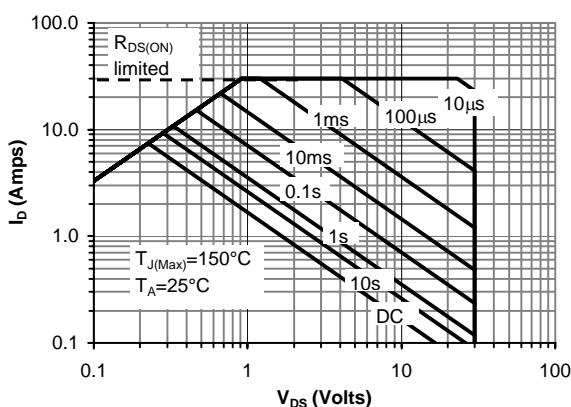
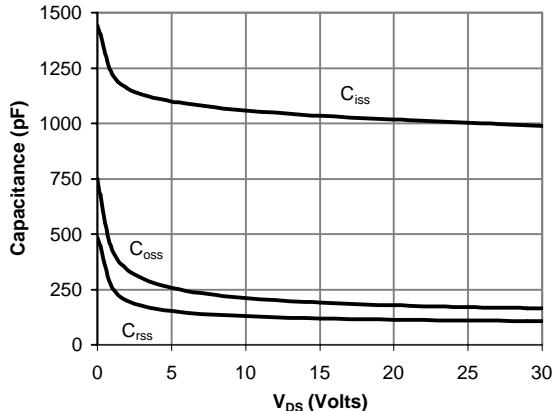
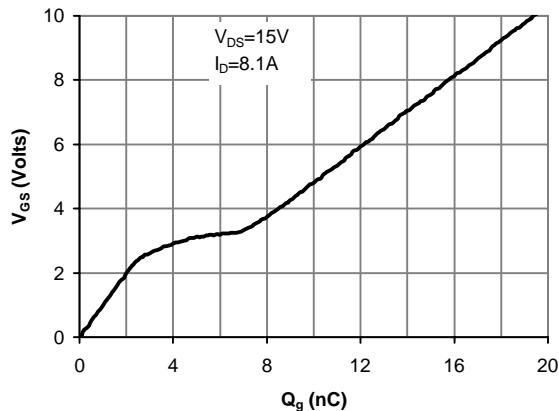
E. These tests are performed with the device mounted on 1 in <sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The SOA curve provides a single pulse rating.

Rev 0 : July 2005

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**N-CH TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**

## N-CH TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



**P-Channel Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$I_D=-250\mu\text{A}, V_{GS}=0\text{V}$	-30			V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS}=-24\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			-1 -5	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm20\text{V}$			$\pm100$	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-1.4	-2	-2.7	V
$I_{\text{D(ON)}}$	On state drain current	$V_{GS}=-10\text{V}, V_{DS}=-5\text{V}$	30			A
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{GS}=-10\text{V}, I_D=-7.1\text{A}$ $T_J=125^\circ\text{C}$		20 27	25 33	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}, I_D=-5.6\text{A}$		29	40	$\text{m}\Omega$
$g_{\text{FS}}$	Forward Transconductance	$V_{DS}=-5\text{V}, I_D=-7.1\text{A}$		19.6		S
$V_{\text{SD}}$	Diode Forward Voltage	$I_S=-1\text{A}, V_{GS}=0\text{V}$		-0.7	-1	V
$I_S$	Maximum Body-Diode Continuous Current				-4.2	A
<b>DYNAMIC PARAMETERS</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=-15\text{V}, f=1\text{MHz}$		1573		pF
$C_{\text{oss}}$	Output Capacitance			319		pF
$C_{\text{rss}}$	Reverse Transfer Capacitance			211		pF
$R_g$	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		6.7		$\Omega$
<b>SWITCHING PARAMETERS</b>						
$Q_g(10\text{V})$	Total Gate Charge (10V)	$V_{GS}=-10\text{V}, V_{DS}=-15\text{V}, I_D=-7.1\text{A}$		30.9		nC
$Q_g(4.5\text{V})$	Total Gate Charge (4.5V)			16.1		nC
$Q_{\text{gs}}$	Gate Source Charge			8		nC
$Q_{\text{gd}}$	Gate Drain Charge			4.4		nC
$t_{\text{D(on)}}$	Turn-On DelayTime	$V_{GS}=-10\text{V}, V_{DS}=-15\text{V}, R_L=2.2\Omega, R_{\text{GEN}}=3\Omega$		9.5		ns
$t_r$	Turn-On Rise Time			8		ns
$t_{\text{D(off)}}$	Turn-Off DelayTime			44.2		ns
$t_f$	Turn-Off Fall Time			22.2		ns
$t_{\text{rr}}$	Body Diode Reverse Recovery Time	$I_F=-7.1\text{A}, dI/dt=100\text{A}/\mu\text{s}$		25.5		ns
$Q_{\text{rr}}$	Body Diode Reverse Recovery Charge	$I_F=-7.1\text{A}, dI/dt=100\text{A}/\mu\text{s}$		14.7		nC

A: The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in <sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The value in any given application depends on the user's specific board design. The current rating is based on the  $t \leq 10\text{s}$  thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C. The  $R_{\theta JA}$  is the sum of the thermal impedance from junction to lead  $R_{\theta JL}$  and lead to ambient.

D. The static characteristics in Figures 1 to 6,12,14 are obtained using 80  $\mu\text{s}$  pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in <sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The SOA curve provides a single pulse rating.

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## P-CH TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

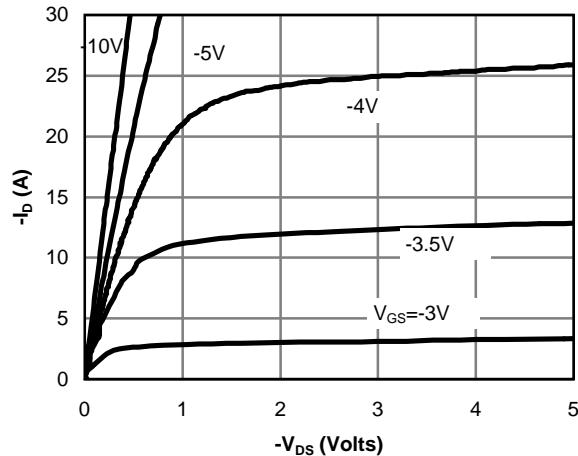


Fig 16: On-Region Characteristics

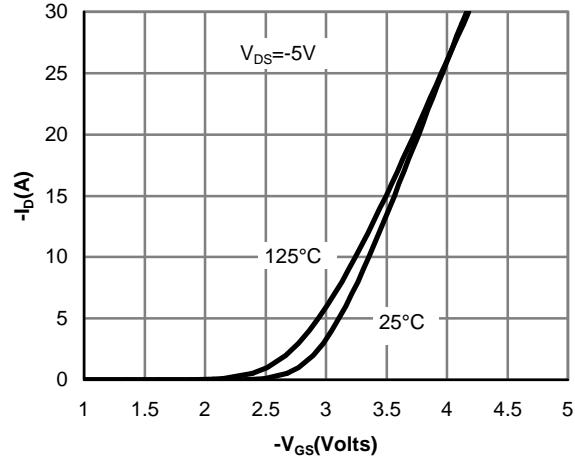


Figure 17: Transfer Characteristics

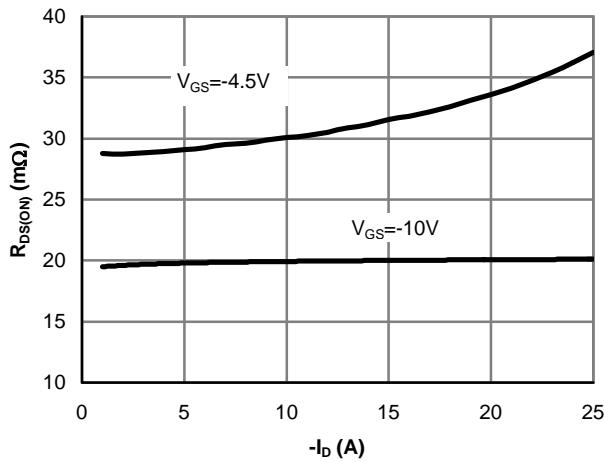


Figure 18: On-Resistance vs. Drain Current and Gate Voltage

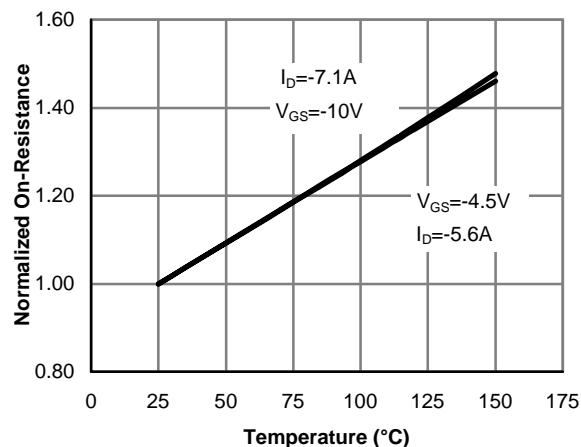


Figure 19: On-Resistance vs. Junction Temperature

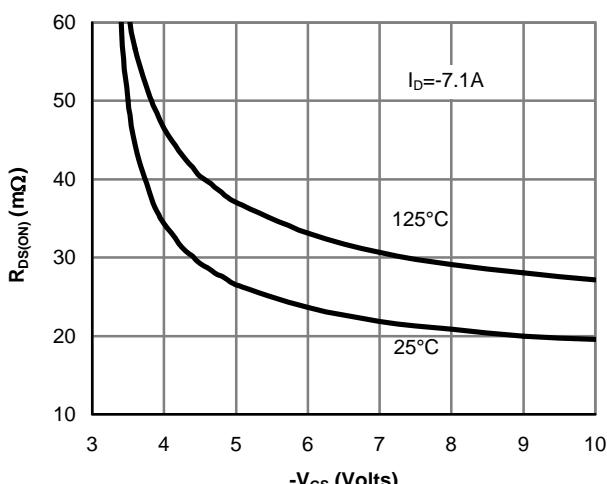


Figure 20: On-Resistance vs. Gate-Source Voltage

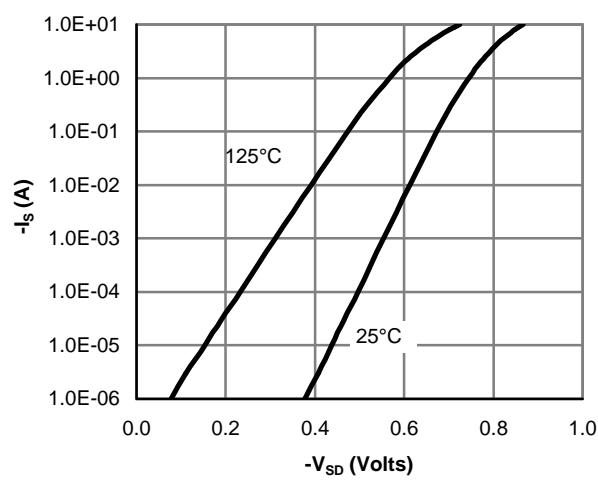


Figure 21: Body-Diode Characteristics

## P-CH TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

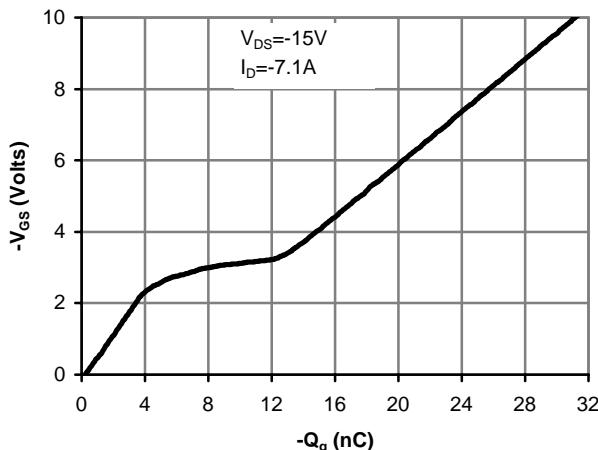


Figure 22: Gate-Charge Characteristics

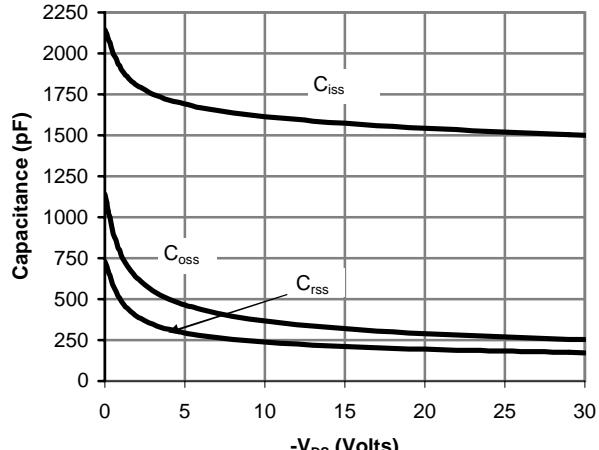


Figure 23: Capacitance Characteristics

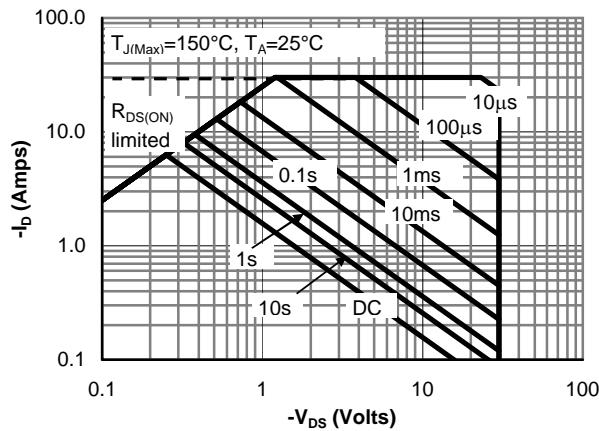


Figure 24: Maximum Forward Biased Safe Operating Area (Note E)

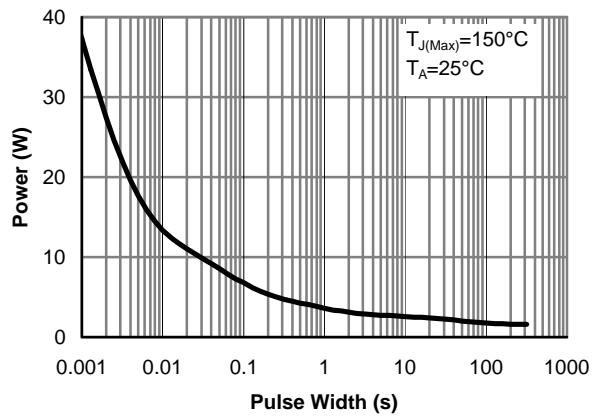


Figure 25: Single Pulse Power Rating Junction-to-Ambient (Note E)

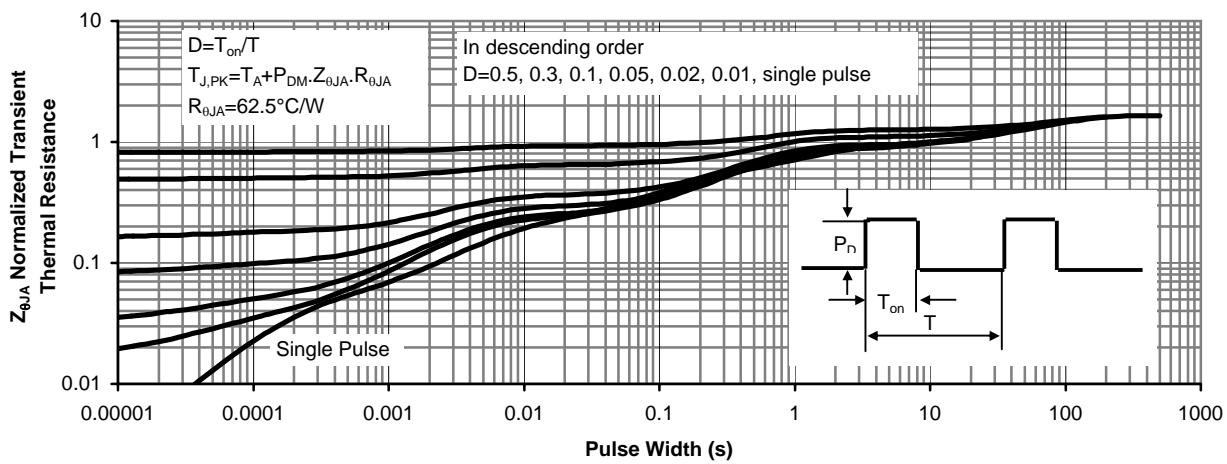


Figure 26: Normalized Maximum Transient Thermal Impedance

ООО "ЛайфЭлектроникс"

"LifeElectronics" LLC

ИНН 7805602321 КПП 780501001 Р/С 40702810122510004610 ФАКБ "АБСОЛЮТ БАНК" (ЗАО) в г.Санкт-Петербурге К/С 30101810900000000703 БИК 044030703

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибуторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибуторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помочь разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



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